EPOXY BACKFILL SYSTEM

(Low Density)

HPX-850

Epoxy

HPX-850 is a light weight, heat resistant, two component epoxy backfill system. Like BC 7020, the filler portion is pre-blended into the resin and hardener components for easier handling, thus simplifying the mixing process.

HPX-850 features advantages such as low cost, long pot life, machineability, and low shrinkage.

HPX-850 is ideally suited for numerous applications involving mold and core construction.

WORKING PROPERTIES

Mix Ratio (Resin/Hardener)	6 to 1 by wt.
Viscosity (Brookfield @ 75°F) Mixed	Paste
Pot Life (1/2 lb. mass) @ 75°F	2-2.5 Hours
Color, Resin	Dark Gray
Color, Hardener	Brown
Color, Mixed	Gray

CURE SCHEDULE

HPX-850 can be removed from the mold after allowing to set 24 hours @ room temperature (75°F). Post cure for applications requiring temperatures above 150°F can be accomplished in an oven or in use by a gradual heat rise; 2 hours @ 150°F, plus 2 hours @ 250°F, plus 2 hours at 300°F.

PHYSICAL PROPERTIES

Specific Gravity (gms/cc)	0.82
Cubic inches/lb. of product	34
Lbs./Cubic inch of product	0.03
Hardness (Shore D) @ 75°F	74
Ultimate Compressive Strength (psi)	4,980
Deflection Temperature (264 psi) °F	285
Shrinkage, Linear (ASTM-D-2566-69)	0.0002 in./in.

* To be determined

HPX-850
MIXING PROCEDURE

Combine resin & hardener (by weight) into a clean, dry mixing container such as a Hobart Kettle or similar vessel. Mix completely (5 - 10 minutes) until components yield a uniform color. Empty mixture into mold cavity in 1 to 2 inch layers and compact (tamp) into place.

Note: *To insure adhesion between previous applied surface coat, laminate or HPX-850 backfill system, it is recommended that a thin layer of epoxy resin/hardener mixture be used prior to back filling with the HPX-850 system.*